<u>**Amendments to the Claims:**</u>

This listing of claims will replace all prior versions, and listings, of claims in the application.

<u>**Listing of Claims:**</u>

1. (Currently Amended) A microstructured component having a layered construction, comprising:

a carrier including at least one glass layer;

a component structure including a first silicon layer directly bonded to the glass layer, the component structure including movable structure elements; and

a cap arranged over the component structure and bonded directly to the glass layer, wherein the component structure includes a first silicon wafer and is bonded to the glass layer by anodic bonding at a temperature of approximately 400° C, ~~and~~ wherein the first silicon layer has a thickness greater than 50 μm, wherein the cap is configured as a mechanical stop for the movable structure elements, wherein the component structure is enclosed in a vacuum between the glass layer and the cap, and wherein a pressure of the vacuum is approximately 100 μbar to 1 mbar.

Claims 2 to 3. (Canceled).

4. (Original) The microstructured component of claim 1, wherein the first silicon wafer includes a (111)-silicon wafer.

5. (Original) The microstructured component of claim 1, wherein the cap includes a second silicon wafer and is bonded to the glass layer by anodic bonding.

6. (Original) The microstructured component of claim 1, further comprising conductor paths arranged to contact the component structure arranged between the glass layer and the component structure.

7. (Original) The microstructured component of claim 1, further comprising at least one electrically conductive shield arranged on the glass layer, at least part of the component structure electrically connected to the shield.

8. (Original) The microstructured component of claim 7, wherein the glass layer includes a structured metallization in which conductor paths and shields are arranged.

Claims 9 to 21. (Canceled).

22. (Previously Presented) The microstructured component of claim 1, wherein the microstructured component is a yaw rate sensor.